

1.0A Surface Mount ; YbYfU` Di fdcgY Rectifiers -50V- 1000V  
SC8!%&' !@PACKAGE

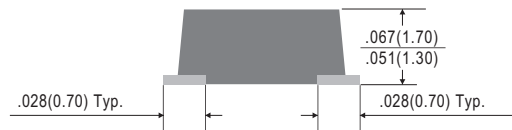
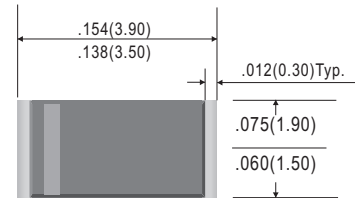
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Tiny plastic SMD package.
- High current capability.
- High surge capability.
- Glass passivated chip junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- **Pb-Free package is available**  
RoHS product for packing code suffix "G"  
Halogen free product for packing code suffix "H"

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123<sup>ES</sup> / MINI SMA
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.018 gram

SOD-123<sup>ES</sup>



Dimensions in inches and (millimeters)

### Maximum ratings and Electrical Characteristics (AT T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I <sub>O</sub>			1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I <sub>FSM</sub>			30	A
Reverse current	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 25°C	I <sub>R</sub>			5.0	μA
	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 125°C				50	
Thermal resistance	Junction to ambient	R <sub>θJA</sub>		60		°C/W
	Junction to case	R <sub>θJC</sub>		30		
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C <sub>J</sub>		15		pF
Rating for fusing (t < 8.3 ms) Note1		I <sup>2</sup> t			3.7	A <sup>2</sup> s
Storage temperature		T <sub>STG</sub>	-65		+175	°C

Note 1: For device using on bridge rectifier appliaction

SYMBOLS	V <sub>RRM</sub> <sup>*1</sup> (V)	V <sub>RMS</sub> <sup>*2</sup> (V)	V <sub>R</sub> <sup>*3</sup> (V)	V <sub>F</sub> <sup>*4</sup> (V)	Operating temperature T <sub>J</sub> , (°C)
FM4001-M	50	35	50	1.10	-55 to +150
FM4002-M	100	70	100		
FM4003-M	200	140	200		
FM4004-M	400	280	400		
FM4005-M	600	420	600		
FM4006-M	800	560	800		
FM4007-M	1000	700	1000		

- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage@I<sub>F</sub>=1.0A

## Rating and characteristic curves

FIG.1-TYPICAL FORWARD CHARACTERISTICS

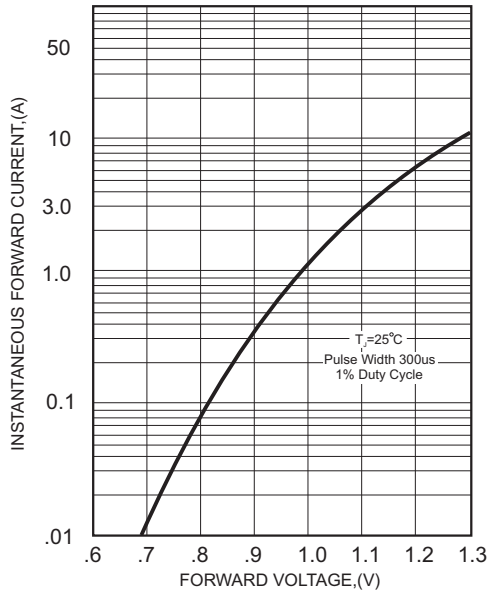


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

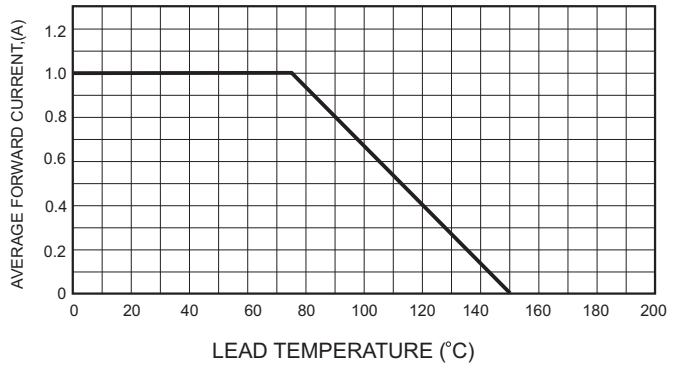


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

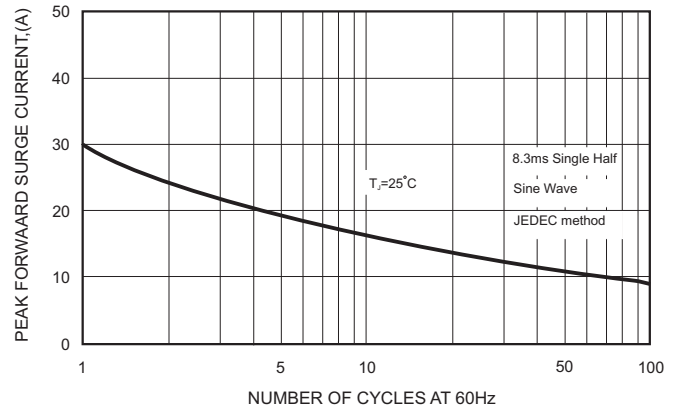


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

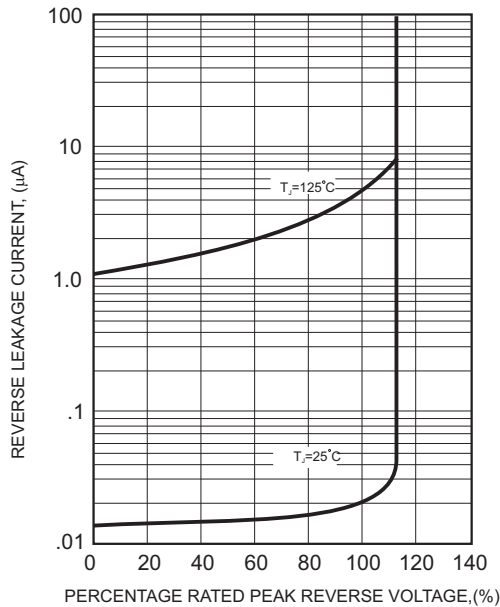
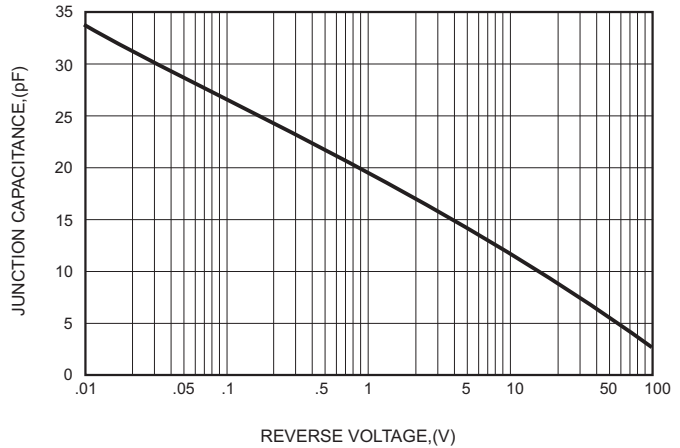




FIG.5-TYPICAL JUNCTION CAPACITANCE



1.0A Surface Mount ; YbYfU` Di fdcgY Rectifiers -50V- 1000V  
SC8!%&' !@PACKAGE

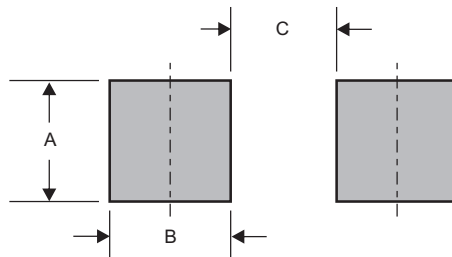
**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

**Marking**

Type number	Marking code
FM4001-M	A1
FM4002-M	A2
FM4003-M	A3
FM4004-M	A4
FM4005-M	A5
FM4006-M	A6
FM4007-M	A7

**Suggested solder pad layout**



Dimensions in inches and (millimeters)

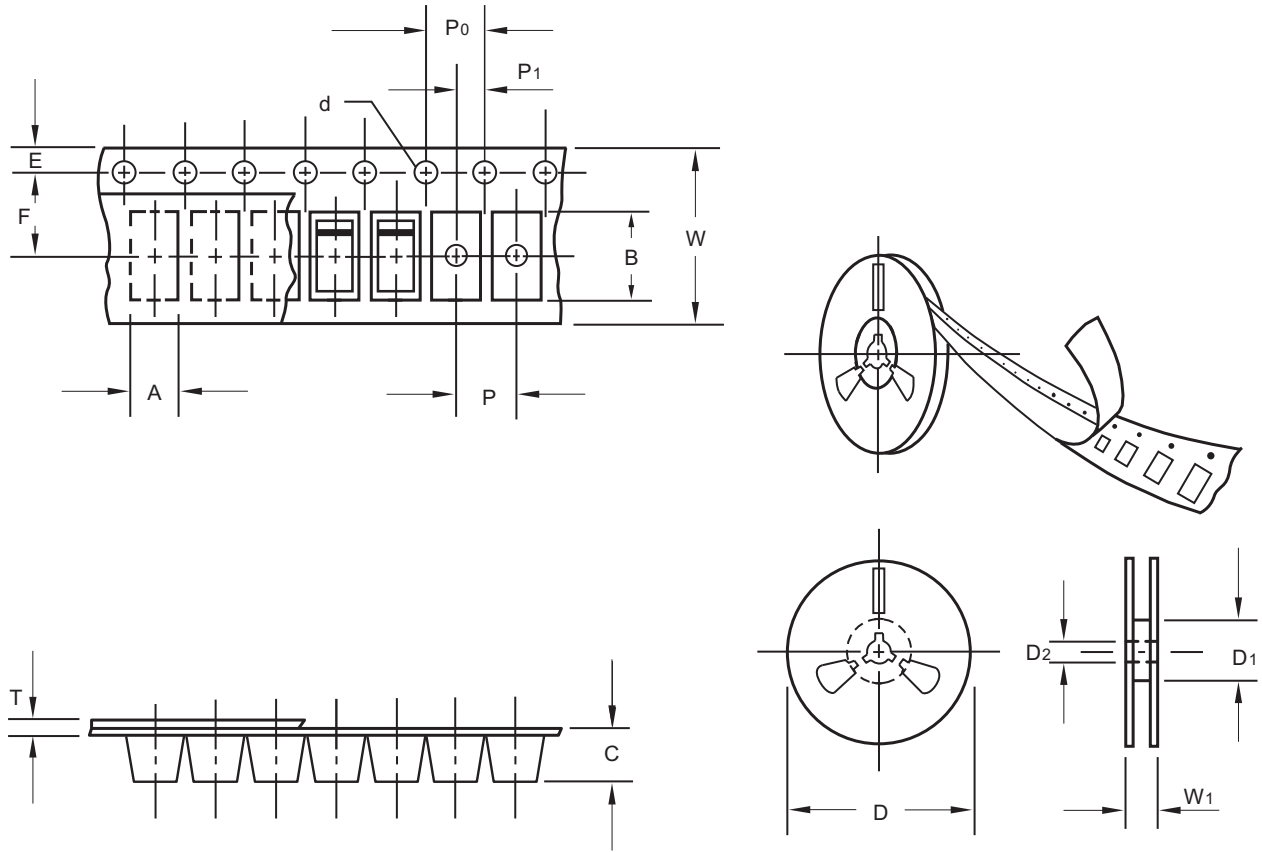
PACKAGE	A	B	C
SOD-123-L	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)

**Reel packing**

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123-L	7"	2,500	4.0	25,000	183*183*123	178	382*262*387	200,000	9.5

**1.0A Surface Mount ; YbYfU` DI fdcgY Rectifiers -50V- 1000V  
SC8!%&' !@PACKAGE**

**Packing information**



unit:mm

Item	Symbol	Tolerance	SOD-123-L
Carrier width	A	0.1	1.90
Carrier length	B	0.1	3.90
Carrier depth	C	0.1	1.68
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.